Title (en)

Chip resistor for surface mounting and method of manufacturing a chip resistor for surface mounting

Title (de)

Oberflächenmontierbarer Chip-Widerstand und Verfahren zu seiner Herstellung

Title (fr)

Résistance pour chip monté en surface et procédé pour sa production

Publication

EP 1619696 A3 20071003 (EN)

Application

EP 05253599 A 20050610

Priority

GB 0416510 A 20040723

Abstract (en)

[origin: EP1619696A2] The present invention relates to a leadless chip resistor for surface mounting on a circuit board. Conventional leadless chip resistors have a single resistor layer 20 on the upper surface thereof between two conductive plates 50. The present invention proposes a double sided resistor chip, which has resistor layers 20, 320 on both upper and lower faces of the substrate 10 and in conductive contact with electroplated conductive plates 50 which wrap around the ends of the substrate 10. This allows the resistor chip to have a higher pulse energy rating then a conventional surface mounted resistor of the same size. A method of manufacturing the resistor chip is also disclosed.

IPC 8 full level

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CPC (source: EP)

H01C 1/148 (2013.01); **H01C 7/003** (2013.01); **H01C 17/006** (2013.01)

Citation (search report)

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Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU MC NL PL PT RO SE SI SK TR

Designated extension state (EPC)

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EP 1619696 A2 20060125; **EP 1619696 A3 20071003**; GB 0416510 D0 20040825

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